

# HSB278S

Silicon Schottky Barrier Diode for Detector

REJ03G0596-0100 (Previous: ADE-208-1383) Rev.1.00 Apr 12, 2005

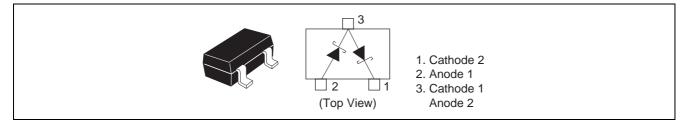
### Features

- Low forward voltage, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB278S	S2	СМРАК	PTSP0003ZB-A (CMPAK)

### Pin Arrangement





# **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V
Reverse voltage	V <sub>R</sub>	30	V
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>1</sup> * <sup>2</sup>	200	mA
Peak forward current	I <sub>FM</sub> * <sup>2</sup>	150	mA
Average rectified current	lo * <sup>2</sup>	30	mA
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. 10 ms sine wave 1 pulse.

2. Per one device.

# Electrical Characteristics \*1

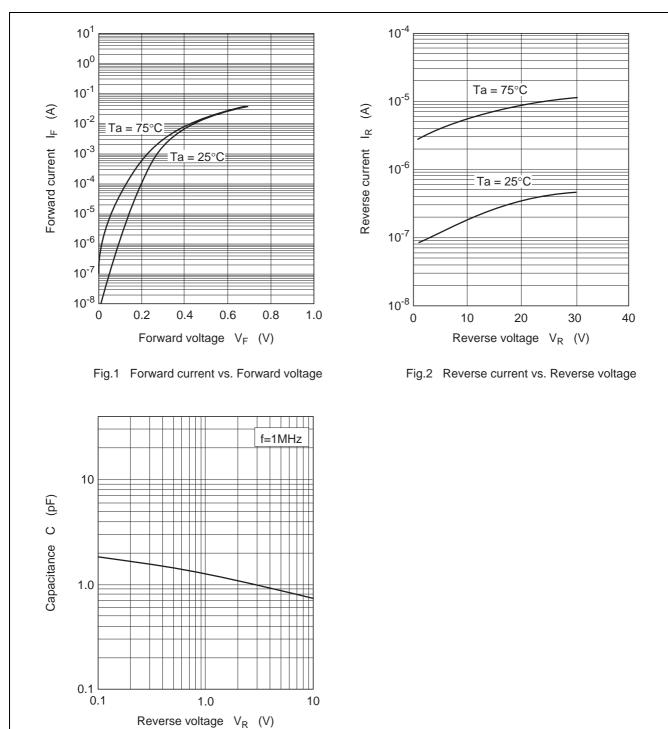
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	—		0.30	V	I <sub>F</sub> = 1 mA
	V <sub>F2</sub>	—		0.95		I <sub>F</sub> =30 mA
Reverse current	I <sub>R</sub>	—		700	nA	V <sub>R</sub> = 10 V
Capacitance *2	С	—		1.50	pF	$V_R = 1 V, f = 1 MHz$
ESD-Capability *1	—	100	_	—	V	C = 200 pF, $R_L = 0 \Omega$ , Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ;  $I_R > 1.4 \ \mu A$  at  $V_R$  = 10 V



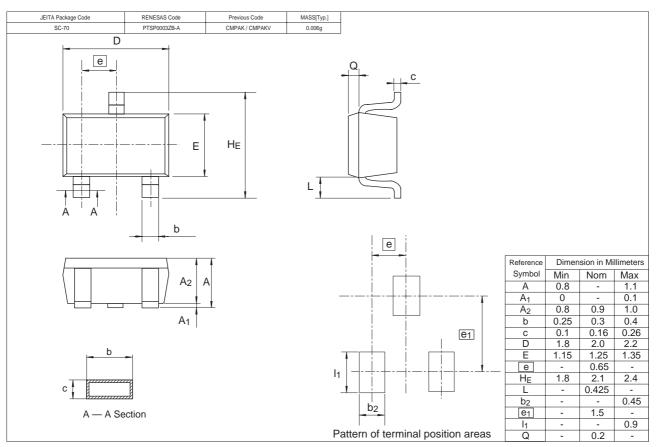


### **Main Characteristic**

Fig.3 Capacitance vs. Reverse voltage



# Package Dimensions





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